

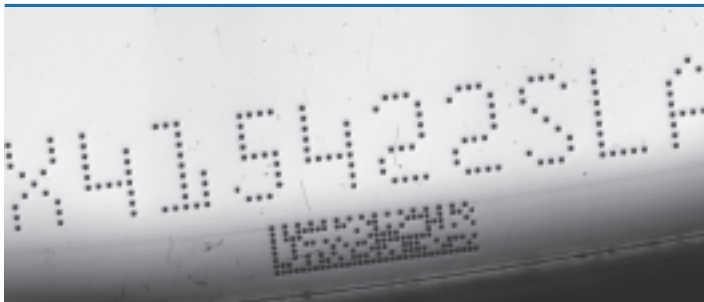
Wafer ID Marker

WID-SERIES

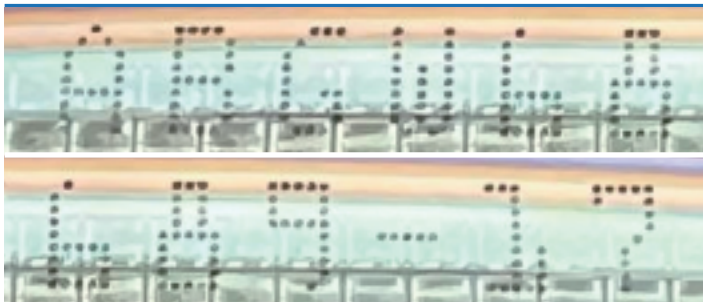
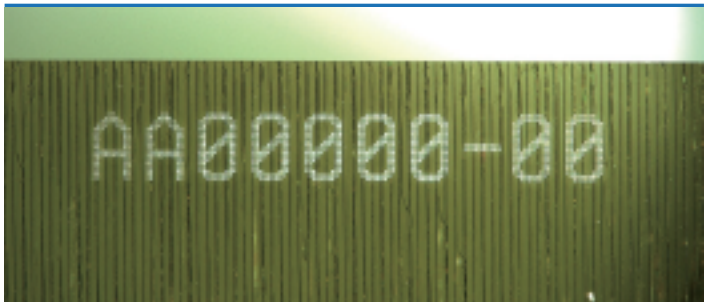
Applications

E&R WID-200/300AG provide great quality of ID marking on different type of material wafers.

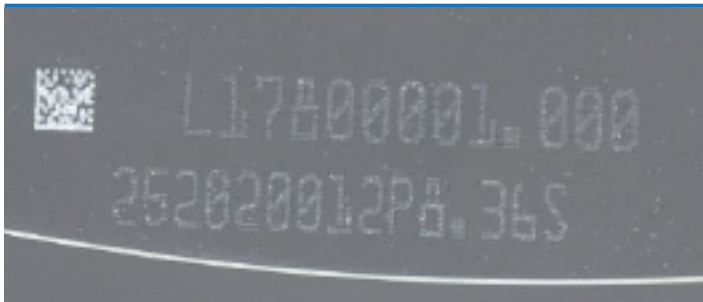
Si wafer marking



SiC wafer marking



Glass wafer marking



Specification for WID-series

Marking Performance	
Marking Modes	Softmark (Dark Mark), Hardmark (White Mark), Dot Matrix
Fonts	SEMI M12, M13, Dot Matrix
	Barcode SEMI412, IBM412
	2D Code SEMI T7
	Customized designs
Checksum	SEMI, IBM, customized (optional)
Repeatability	± 120, ± 50um(Optional)
WPH	120
Marking Capability	Background, Polished, Coated, Oxidized, Nickel, Glass wafer
Depth of Marking	0.1-100um



Wafer Handling

Wafer Size	WID-300 for 8" 12"
	WID-200 for 6" 8"
Wafer Thickness	≥ 250um
Load Port	WID-300 : FOUP or Open Cassette x 2
	WID-200 : Open Cassette x 3
Alignment	Optical alignment for both flatted and notched wafers

Laser Unit

Laser Type	IR laser, 1064nm Wavelength
	Green laser, 532 nm Wavelength, TEM ₀₀
	UV Laser, 355 nm Wavelength, TEM ₀₀
Cooling	Water Cooling for Green/UV, Air Cooling for IR/Green/UV
Effective Marking Area	Max 100 x 100mm
Diode lifetime	16000hr or more
Auto Power Regulation	Yes

Utilities

Dimension (main module)	1490 (W) x 1800 (D) x 1850 (H) mm
Electricity Power	220VAC ±10%, 3 Phases, 50/60Hz, 40A
Oil free compressed air	> 6 bar
Exhaust	2 Nm ³ / hr

Workstation

Operator System	English / Chinese
Communication	SECS II / GEM Interface optional

